



ASSOCIATION CONNECTING
ELECTRONICS INDUSTRIES

IPC-6011

Generic Performance Specification for Printed Boards

IPC-6011

July 1996

A standard developed by IPC

Supersedes IPC-RB-276

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In May 1995 the IPC's Technical Activities Executive Committee adopted Principles of Standardization as a guiding principle of IPC's standardization efforts.

Standards Should:

- Show relationship to Design for Manufacturability (DFM) and Design for Engineering (DFE)
- Minimize time to market
- Contain simple (simplified) language
- Just include spec information
- Focus on end product performance
- Include a feedback system on use and problems for future improvement

Standards Should Not:

- Inhibit innovation
- Increase time-to-market
- Keep people out
- Increase cycle time
- Tell you how to make something
- Contain anything that cannot be defended with data

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Adopted October 6, 1998

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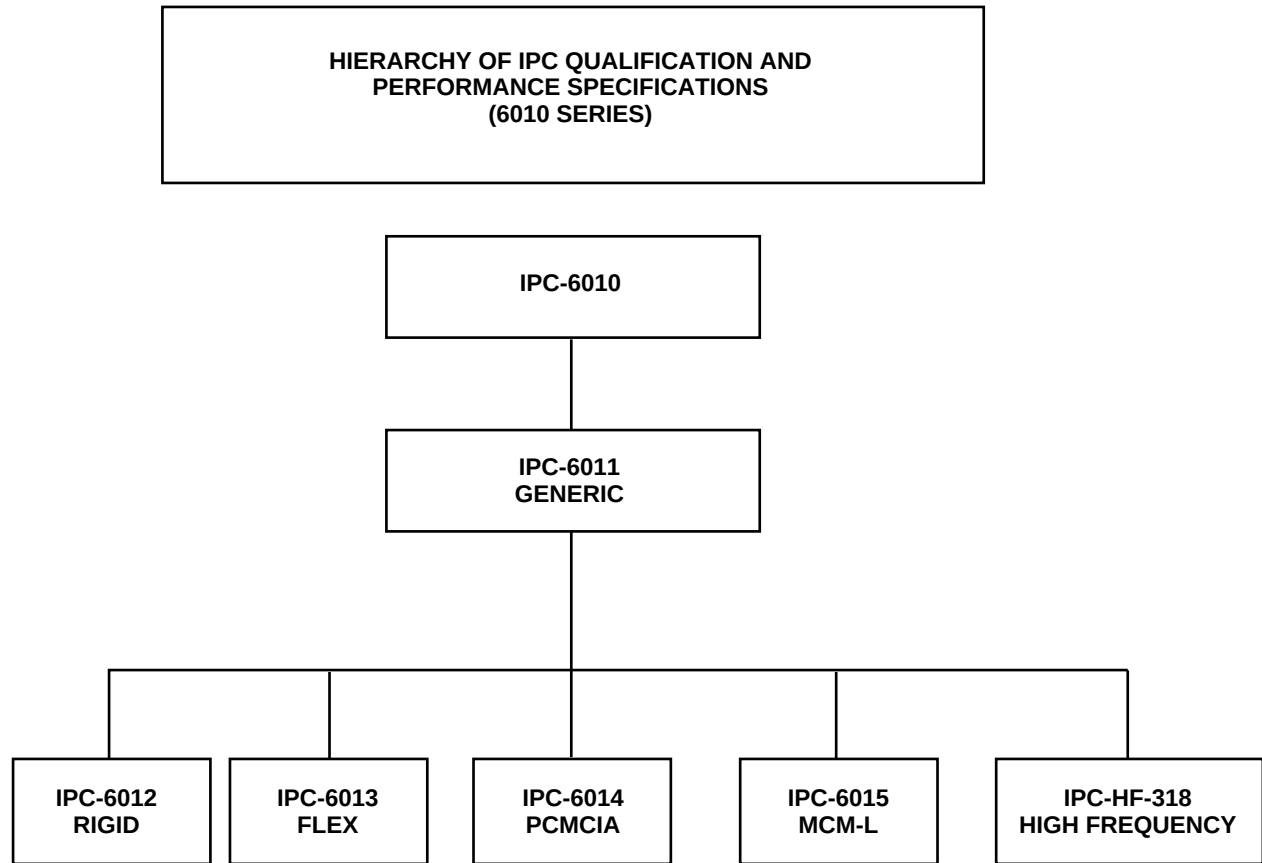
Developed by the Performance Specifications Task Group (D-33a)
of the Rigid Printed Board Committee of IPC

Users of this standard are encouraged to participate in the
development of future revisions.

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Foreword

IPC's documentation strategy is to provide distinct documents that focus on specific aspects of electronic packaging issues. In this regard document sets are used to provide the total information related to a particular electronic packaging topic. A document set is identified by a four digit number that ends in zero (0) (i.e., IPC-6010).

This standard is intended to provide information on the generic specifications for printed boards. This information must also be supplemented by a performance specification that contains the requirements for the chosen technology. When used together, these documents should lead both manufacturer and customer to consistent terms of acceptability.

This document, combined with one of the performance specifications, form the documentation package which supersedes the following:

IPC-6012 supersedes IPC-RB-276

IPC-6013 supersedes IPC-RF-245 and IPC-FC-250

As technology changes, a performance specification will be updated, or new focus specifications will be added to the document set. The IPC invites input on the effectiveness of the documentation and encourages user response through completion of "Suggestions for Improvement" forms at the end of each document.

Acknowledgment

Any Standard involving a complex technology draws material from a vast number of sources. While the principal members of the

Performance Specifications Task Group of the IPC Rigid Printed Board Committee are shown below, it is not possible to include all of those

who assisted in the evolution of this standard. To each of them, the members of the IPC extend their gratitude.

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